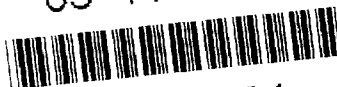


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1. Name of conveying party(ies):

1) Gyu Hwan CHOI

MRD  
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Additional name(s) of conveying party(ies) attached?

2. Name and address of receiving party(ies):

Name: Samsung Electro-Mechanics Co., Ltd.

Internal Address:

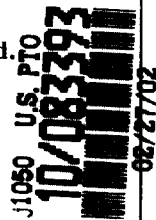
Street Address: 314 Maetan-3-dong, Paldal-ku

City: Suwon

State or Area: Kyungki-do

Zip/Postal Code:

Country: Republic of Korea



Execution Date: February 14, 2002

Additional name(s) &amp; address(es) attached?

4. Application number(s) or patent number(s):

10083393

If the document is being filed together with a new application, the execution date of the application is: February 14, 2002

A. Patent Application No(s).

B. Patent No(s).

Additional numbers attached?

5. Name and address of party to whom correspondence concerning document should be mailed:

Name:

LOWE HAUPTMAN GILMAN &amp; BERNER (22429)

Internal Address:

Street Address: 1700 Diagonal Road, Suite 310

City: Alexandria State: VA ZIP: 22314

6. Total number of applications and patents involved: one

7. Total fee (37 CFR 3.41)

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February 27, 2002  
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03/05/2002 EFLORES 00000095 10083393

04 FC:581

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PATENT  
REEL: 012642 FRAME: 0428

**ASSIGNMENT**

In consideration of the premises and other good and valuable consideration in hand paid, the receipt and sufficiency of which is hereby acknowledged, the undersigned,

(1) <u>CHOI, Gyu Hwan</u>	(4) _____
(2) _____	(5) _____
(3) _____	(6) _____

who have made a certain new and useful invention, hereby sell, assign and transfer unto

SAMSUNG ELECTRO-MECHANICS CO., LTD.

314 Maetan-3-dong, Paldal-ku, Suwon,

Kyungki-do, Republic of Korea

its successors and assigns (hereinafter designated "ASSIGNEE") the entire right, title and interest for the United States of America as defined in 35 U.S.C. 100 in the invention entitled HEAT SINK OF MODULE WITH BUILT-IN IC

(a) for which an application for United States Letters Patent was filed on \_\_\_\_\_, and identified by United States Serial No. \_\_\_\_\_;  
or

(b) for which an application for United States Letters Patent was executed on \_\_\_\_\_,

and the undersigned hereby authorize and request the United States Commissioner of Patents and Trademarks to issue any and all United States Letters Patent which may be granted therefor and any and all extensions, divisions, reissues, substitutes, renewals, continuations, or continuations-in-part thereof, and the right to all benefits under the International Convention for the Protection of Industrial Property to the said ASSIGNEE, for its interest as ASSIGNEE, its successors, assigns and legal representatives; the undersigned agree that the attorneys of record in said application shall hereafter act on behalf of said ASSIGNEE;

AND the undersigned hereby agree to transfer a like interest, and to

render all necessary assistance in making application for and obtaining original, divisional, reissued or extended Letters Patent of the United States, upon request of the said ASSIGNEE, its successors, assigns and legal representatives, and without further remuneration, in and to any improvements, and applications for patent based thereon, growing out of or related to the said invention; and to execute any papers by the said ASSIGNEE, its successors, assigns and legal representatives, deemed essential to ASSIGNEE's full protection and title in and to the invention hereby transferred.

SIGNED on the dates indicated aside our signatures:

INVENTOR(S)

DATE SIGNED

1) Choi Gyu Hwan  
Name: CHOI, Gyu Hwan

February 14, 2002